

1. Solder ability and Solder Resistance

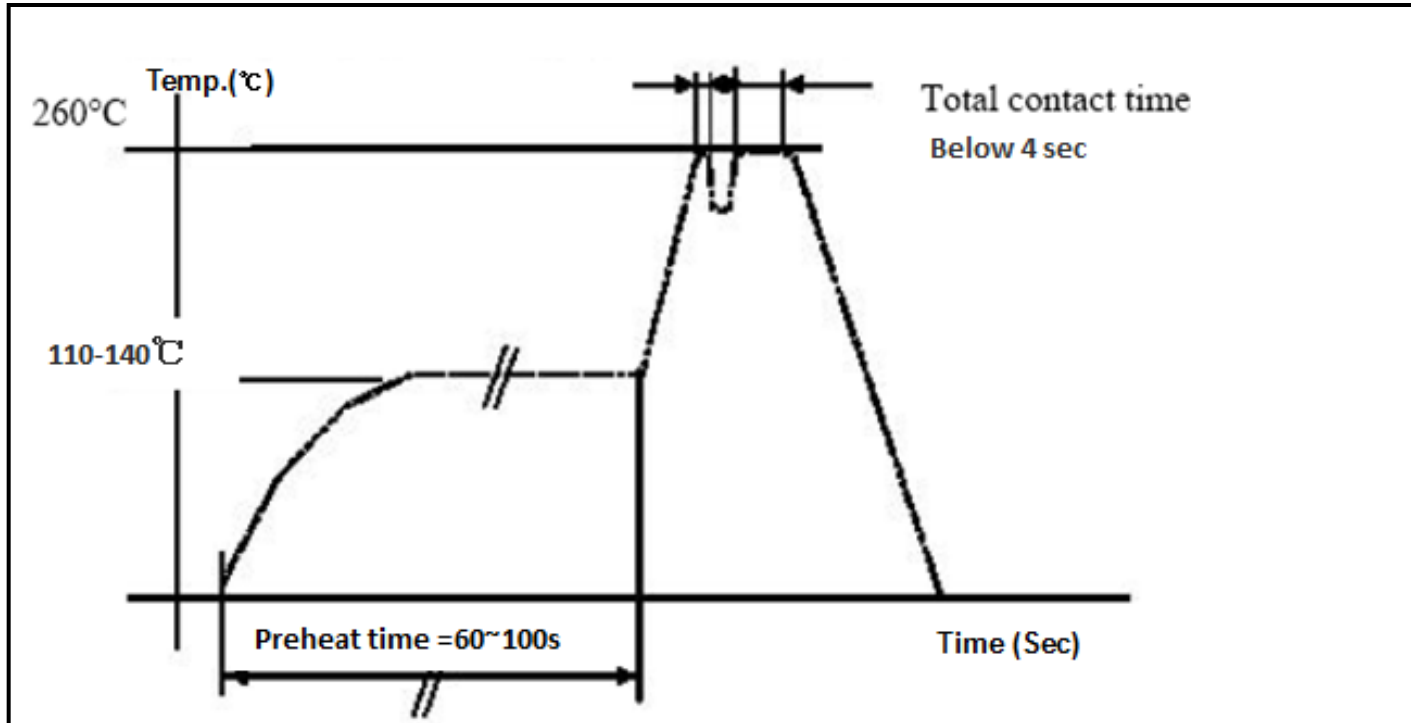
A. Solder ability

Lead solder able per JESD22-B102, method 1) (245°C / 5 seconds, 95% coverage of soldering area guaranteed)

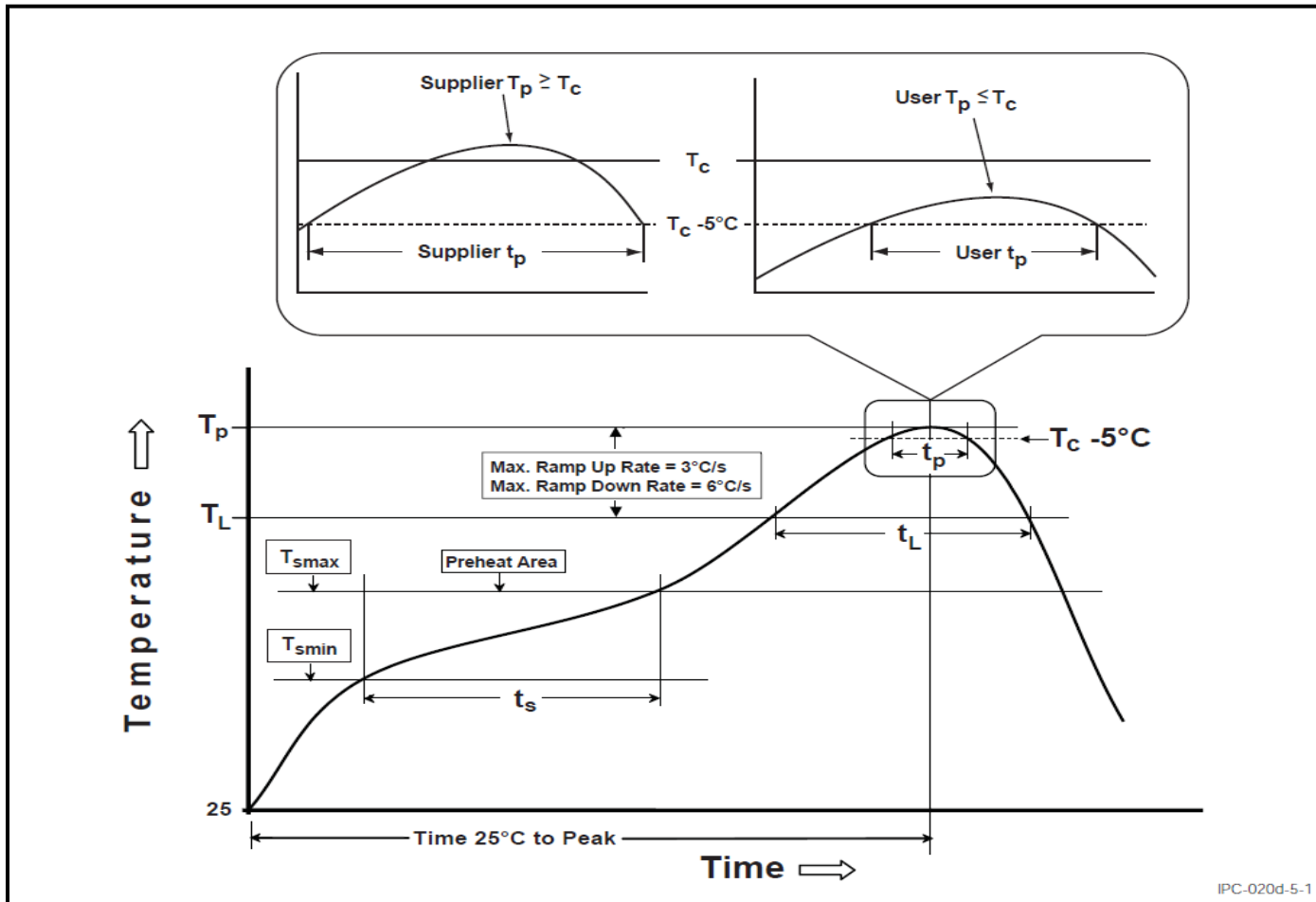
B. Solder Resistance

轴向/插件 : 270°C / 7 sec ; 贴片 : 260±5°C / 10 sec ;

a) Wave Soldering Profile



b) Reflow Soldering Profile (Pb free Application), refer to IPC/JEDEC J-STD-020



Recommended Soldering Profile for Rectifier Diodes (Pb Free)



YANGZHOU YANGJIE ELECTRONIC TECHNOLOGY CO.,LTD.

Preheat/Soak Temperature Min (T _{smin}) Temperature Max (T _{smax}) Time (ts) from (T _{smin} to T _{smax})	50 °C 200 °C 60-120 seconds
Melting Point of Solder (Sn Ag Cu)	217°C
Ramp-up Rate to 217°C(Melting Point of Solder)	3°C/sec
Time at Temp.>217°C (Melting Point of Solder)	60~150 Sec
Peak Temperature	255±5°C
Time within 5°Cbelow Peak Temp.	20~40 Sec
Cooling Rate	6°C/sec (max)
Time from 25°C to Peak Temp.	8min (max)